



GE Energy

Functional Testing Specification

Parts & Repair Services
Louisville, KY

LOU-GENEVA-IS210AEBI

Test Procedure for cards tested on the General Purpose Tester

DOCUMENT REVISION STATUS: Determined by the last entry in the "REV" and "DATE" column

REV.	DESCRIPTION	SIGNATURE	REV. DATE
A	Initial release	F. Howard	02/23/2011
B			
C			

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DATE 02/23/2011	DATE	DATE	DATE 2/23/2011

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Functional test procedure for equipment tested on the GENRAD® GENEVA system

1. SCOPE

1.1 This is a functional testing procedure for various circuit boards.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein. Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check the board's electronic folder for more information.

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires broken or cracked

4.2.1.2 Terminal strips / connectors broken or cracked

4.2.1.3 Loose wires

4.2.1.4 Components visually damaged

4.2.1.5 Capacitors leaking

4.2.1.6 Solder joints damaged or cold

4.2.1.7 Circuit board burned or de-laminated

4.2.1.8 Printed wire runs burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1	H188912	GENRAD Geneva Test System
1	H188805	IS210AEBI Functional Test Fixture
1		ID Chip program

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6. TESTING PROCESS

6.1 Setup and testing

- 6.1.1 These test instructions assume a working knowledge of the Geneva test system. If you are unsure, please get assistance from any member of Team 4.
- 6.1.2 Before testing you should verify that the card does not fall under the Opto-Coupler recall list. Check excel tabs H1, H2, and H3 in the AEBI directory for the list of serial number that have been recalled.
- 6.1.3 Install AEBI test fixture H188805 onto Geneva test system.
- 6.1.4 Open and load the AEBI test program and make connections per instructions.
- 6.1.5 Run the test program. Once a card has passed all steps in test, it is considered to be the latest revision. Tightening certain parameters in the VCO portion of tests was the only change between revisions and the test program tests to the latest revision.
- 6.1.6 If card needs to be upgraded to latest revision, take it to the ID chip programming computer in the Mark VI area and reprogram card to desired revision. See any member of team 4 for assistance if required.

6.2 ***TEST COMPLETE***

7. NOTES

- 7.1 None at this time